

09/768580

**ABSTRACT OF THE INVENTION**

A multi-chip package and a method of manufacturing the same. The multi-chip package of the present invention has a plurality of shelves. A first semiconductor is electrically coupled to at least one of the package's shelves. A second semiconductor die is electrically coupled to at least one of the package's shelves, wherein the second semiconductor die is above said first semiconductor die.

09/768580-01301